SunLED
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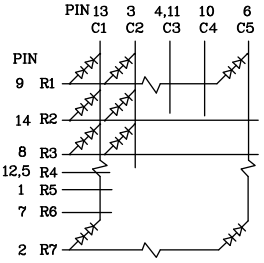
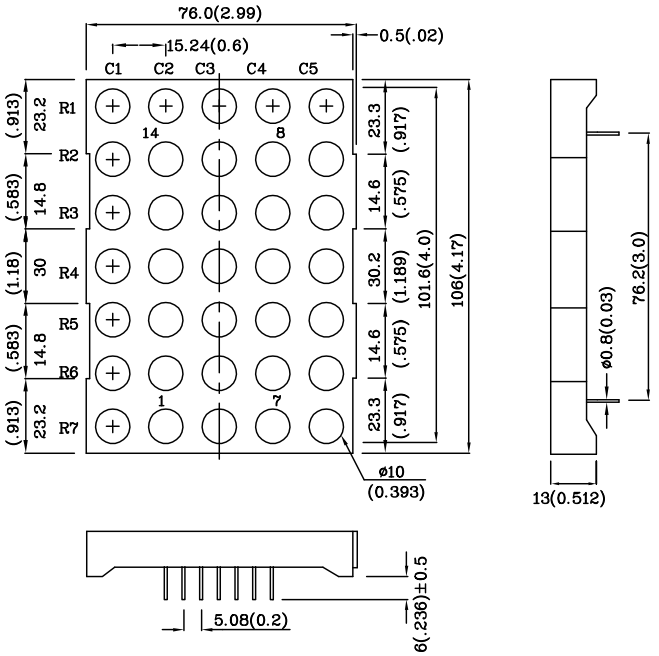
Part Number: **XMUY100C**

101.6mm (4.0") 5x7 DOT MATRIX DISPLAY

Features

- 4.0 INCH MATRIX HEIGHT.
- DOT SIZE 10mm.
- LOW CURRENT OPERATION.
- HIGH CONTRAST AND LIGHT OUTPUT.
- COMPATIBLE WITH ASCII AND EBCDIC CODES.
- STACKABLE HORIZONTALLY.
- COLUMN ANODE AVAILABLE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- MULTICOLOR AVAILABLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE DOT.
- RoHS COMPLIANT.





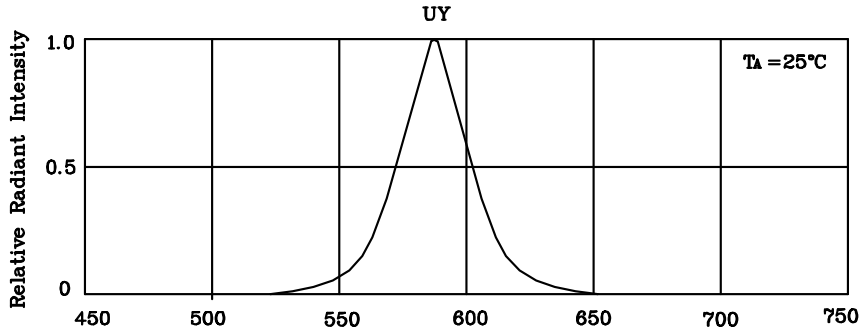
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

Absolute Maximum Ratings (TA=25°C)		**UY (GaAsP/GaP)**	**Unit**
Reverse Voltage Per Segment or (Dp and Comma)	VR	10	V
Forward Current Per Segment or (Dp and Comma)	IF	30	mA
Forward Current (peak) Per Segment or (Dp and Comma) 1/10Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation Per Segment or (Dp and Comma)	PT	150	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm below package base]	260°C For 5 Seconds		

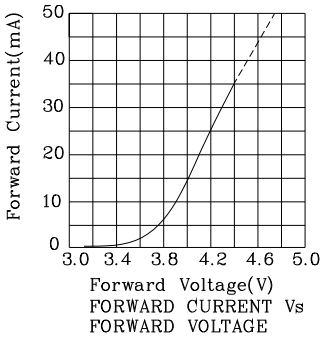
Operating Characteristics (TA=25°C)		**UY (GaAsP/GaP)**	**Unit**
Forward Voltage (typ.) Per Segment or (Dp and Comma) (IF=10mA)	VF	3.9	V
Forward Voltage (max.) Per Segment or (Dp and Comma) (IF=10mA)	VF	5.0	V
Reverse Current (VR=10V)	IR	10	uA
Wavelength of Peak Emission (IF=10mA)	λ P	590	nm
Wavelength of Dominant Emission (IF=10mA)	λ D	588	nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	Δλ	35	nm
Capacitance (VF=0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λ P	Description
			min.	typ.		
XMUY100C	Yellow	GaAsP/GaP	1900	7990	590	Column Cathode

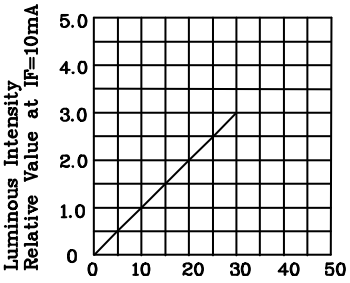


RELATIVE INTENSITY Vs. WAVELENGTH

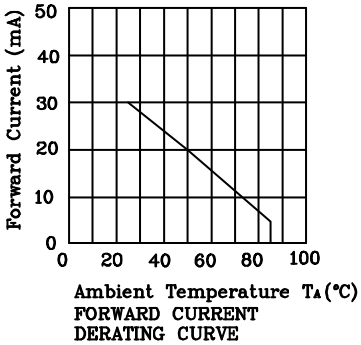
❖ **UY**



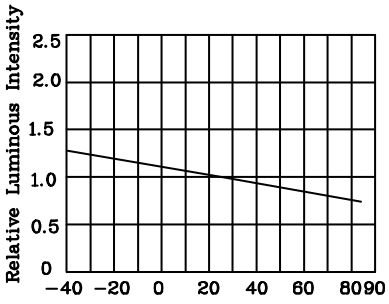
FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

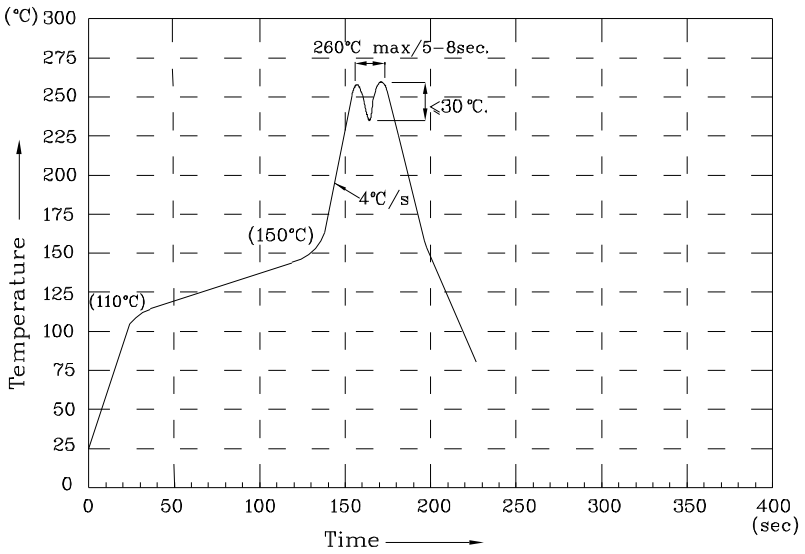


FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245℃~260℃. The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85 degree℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.